

(54) FLAME-RETARDANT ELECTRIC MATERIAL COMPOSITION HAVING EXCELLENT HIGH-SPEED MOLDABILITY

- (11) 62-11746 (A) (43) 20.1.1987 (19) JP
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PURPOSE: To obtain the titled composition having excellent mechanical strength, electrical characteristics and abrasion resistance, by adding a specific amount of an inorganic flame-retardant to a resin component obtained by compounding a specific ethylene-ethyl acrylate copolymer with a specific ethylene- α -olefin copolymer at a specific ratio.

CONSTITUTION: The objective composition can be produced by compounding (A) 70~97 (wt)% ethylene-ethyl acrylate copolymer having a melt index (MI) of 0.2~5g/10 min, preferably 0.5~2g/10 min and an ethyl acrylate content of 5~20%, preferably 10~17% with (B) 3~30T ethylene- α -olefin copolymer (preferably propylene, etc.) having an MI of ≤ 2 g/10 min, preferably 0.01~1.8g/10 min, a density of 0.94~0.97g/cm³ and a melt-tension (MT) at 190°C satisfying the formula $MT \geq 6.0 \times MI^{-0.314}$, and mixing 100pts. (wt.) of the obtained resin composition with (C) 40~150pts., preferably 70~120pts. of an inorganic flame-retardant (preferably magnesium hydroxide, etc., having an average particle diameter of $\leq 20\mu\text{m}$).

EFFECT: A non-polluting composition having low smoking tendency.

USE: Insulation material for communication cable.

(54) FILM FOR HEAT-SEALING

- (11) 62-11747 (A) (43) 20.1.1987 (19) JP
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 (51) Int. Cl. C08L23/08, C08J5/18, C08L23/08, C08L25/06, C08L51/00, C08L53/02

PURPOSE: To provide a heat-sealing film having excellent heat-sealability, releasable easily in opening, and suitable especially for the heat-sealing of a vessel made of a styrene-based resin, by compounding specific components such as ethylene-acrylate copolymer, at specific ratios.

CONSTITUTION: The objective film for heat-sealing is produced from a resin composition composed of (A) 5~50 (wt)% ethylene-acrylate copolymer (preferably containing 5~35% acrylate unit), (B) 5~50% styrene-butadiene block copolymer having styrene content of 10~50% and (C) 10~80% polystyrene and/or a high-impact styrene-butadiene graft copolymer (containing styrene as stem polymer).

(54) RESIN COMPOSITION

- (11) 62-11748 (A) (43) 20.1.1987 (19) JP
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 (51) Int. Cl. C08L23/12, C08K3/22, C08L23/26, C08L29/04

PURPOSE: To provide a resin composition having suppressed thermal degradation of a constituent copolymer in molding and giving a reusable scrap composition such as regrind, by compounding a propylene-based resin, an ethylene-vinyl alcohol copolymer and a hydrotalcite-type compound metal hydroxide.

CONSTITUTION: The objective resin composition can be produced by compounding (A) a propylene-based resin (e.g. isotactic polypropylene) with (B) an ethylene-vinyl alcohol copolymer (preferably a saponified copolymer produced by saponifying an ethylene-vinyl acetate copolymer having an ethylene content of 25~50 mol% to a saponification degree of ≥ 00 mol%) and (C) a hydrotalcite-type compound metal hydroxide (preferably the hydroxide of formula). The ratio of A:B is preferably $10^0:1 \sim 1:10^2$, and the amount of the component C is $10^{-2} \sim 1$ wt% based on the sum of the components A and B.

EFFECT: The scorch, deposition to die face, etc., can be suppressed to give a molded article having excellent appearance and mechanical characteristics.

